

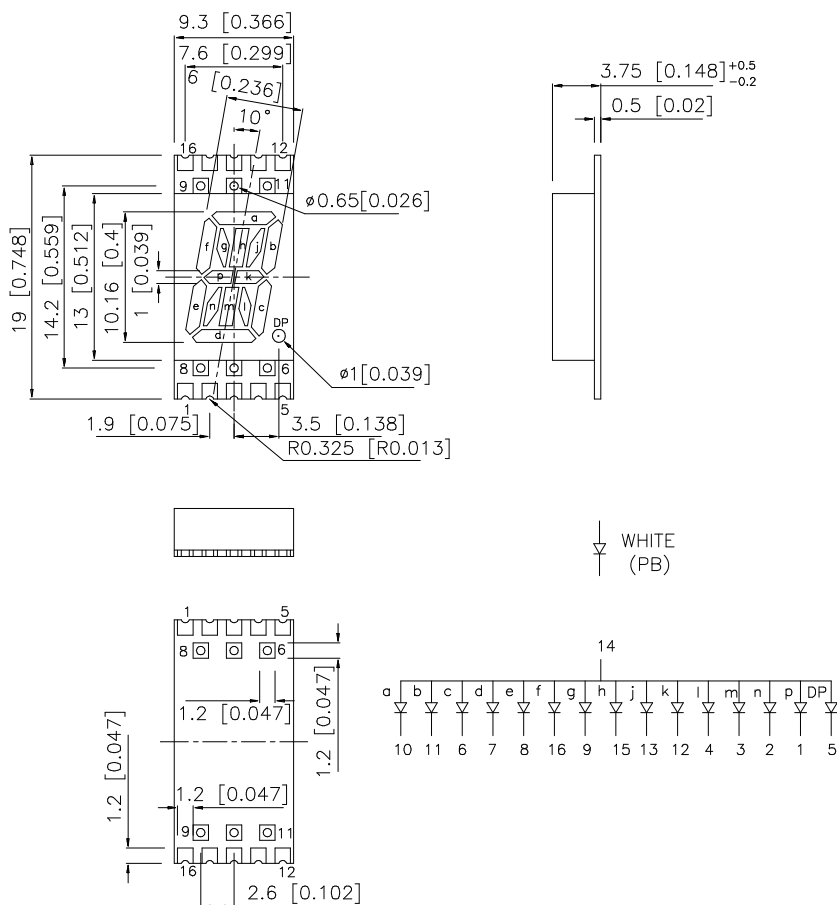
Features

- 0.4 INCH CHARACTER HEIGHT.
- LOW CURRENT OPERATION.
- HIGH CONTRAST AND LIGHT OUTPUT.
- EASY MOUNTING ON P.C. BOARDS OR SOCKETS.
- CATEGORIZED FOR LUMINOUS INTENSITY.
- MECHANICALLY RUGGED.
- STANDARD : GRAY FACE, YELLOW FLUORESCENT SEGMENT.
- PACKAGE : 800PCS / REEL.

Description

The source color devices are made with InGaN on SiC Light Emitting Diode.

Package Dimensions & Internal Circuit Diagram



Notes:

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
2. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (ucd) @ 20 mA		Description
			Min.	Typ.	
APPSA04-41PWFA	WHITE (InGaN)	YELLOW FLUORESCENT	18000	78600	Common Anode,Rt. Hand Decimal

Electrical / Optical Characteristics at T_A=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
V _F	Forward Voltage	White	3.65	4.2	V	I _F =20mA
I _R	Reverse Current	White		10	uA	V _R = 5V
X	Chromaticity Coordinates	White	0.33			
Y			0.34			
C	capacitance	White	65		pF	V _F =0V, f=1 MHz

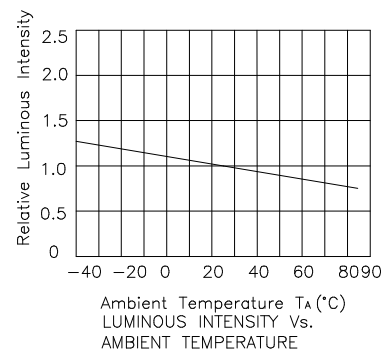
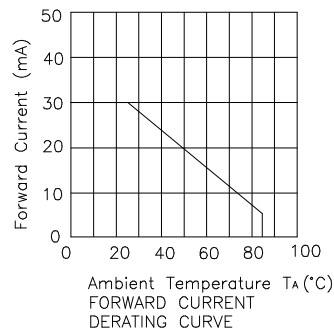
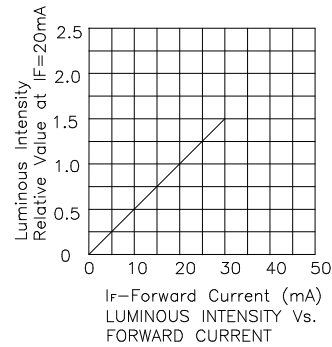
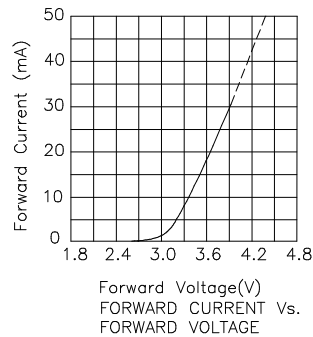
Absolute Maximum Ratings at T_A=25°C

Parameter	White	Units
Power dissipation	102	mW
DC Forward Current	30	mA
Forward Current (Peak)[1]	160	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

Note:

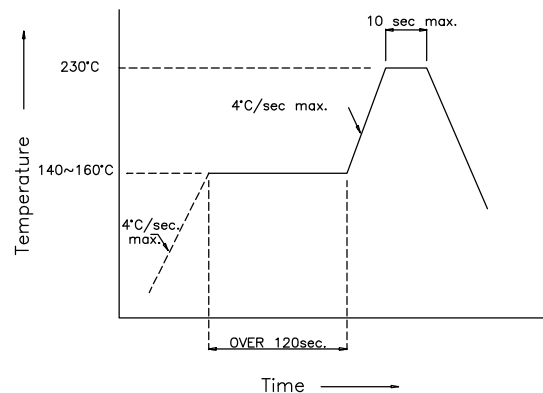
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

White APPSA04-41PWFA

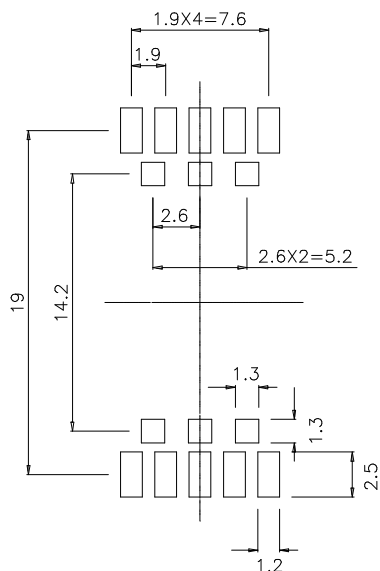


APPSA04-41PWFA SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

